



Title: INSULATED BONDING WIRE FOR MICROELECTRONIC PACKAGING

Inventors: Chia et al.

Application No. 09/687,263 / Attorney Docket No. 00-58510

1 / 4

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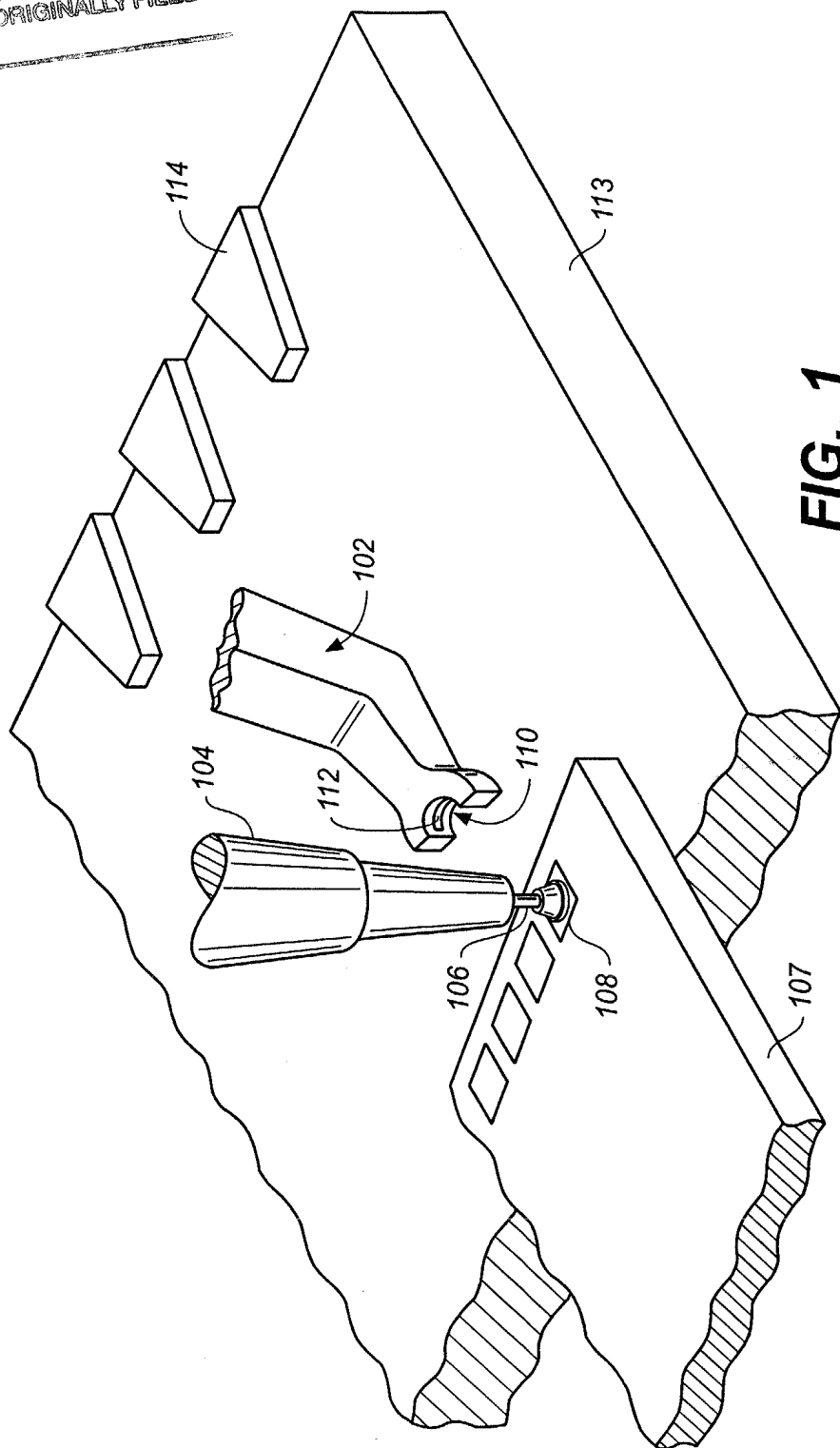


FIG. 1

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2 / 4

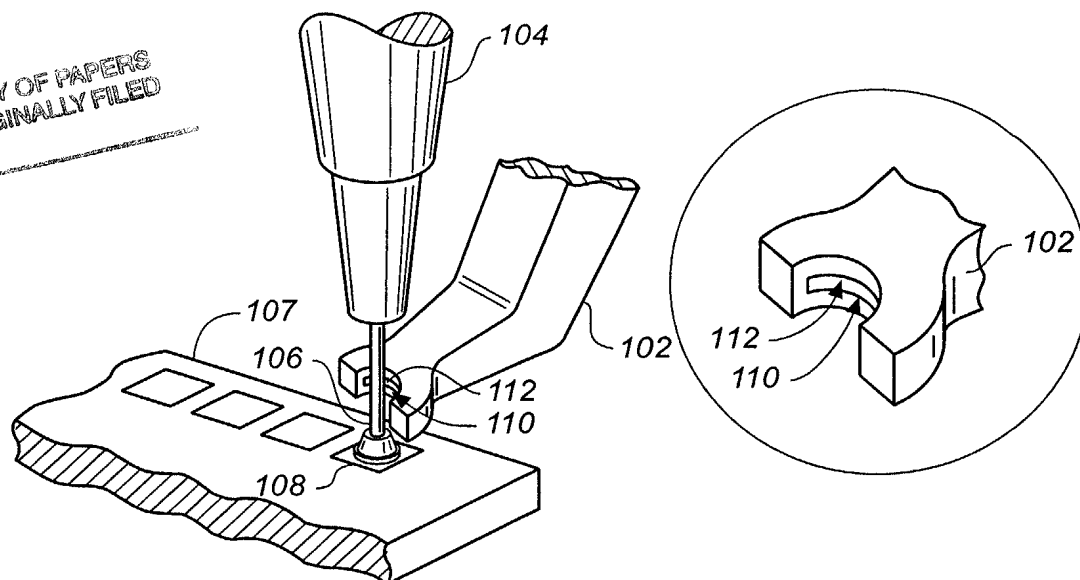


FIG. 2

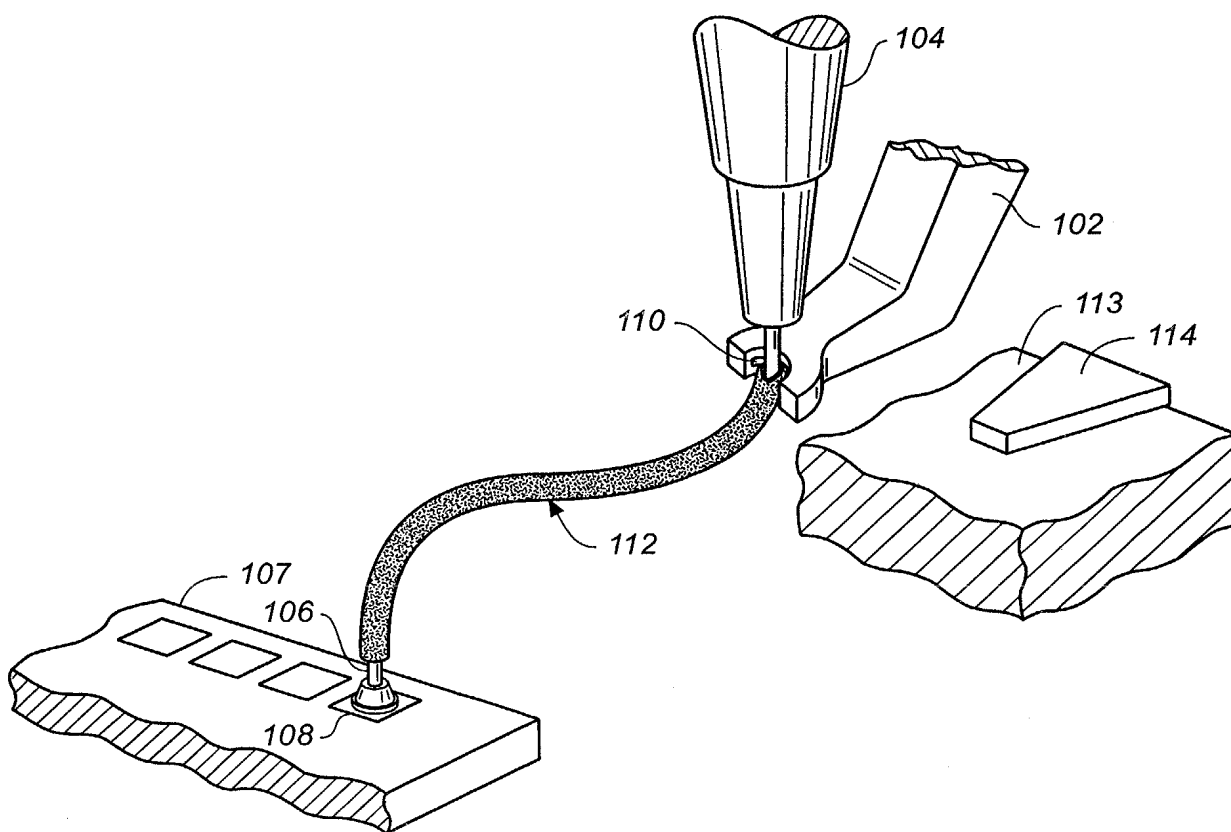


FIG. 3



3 / 4

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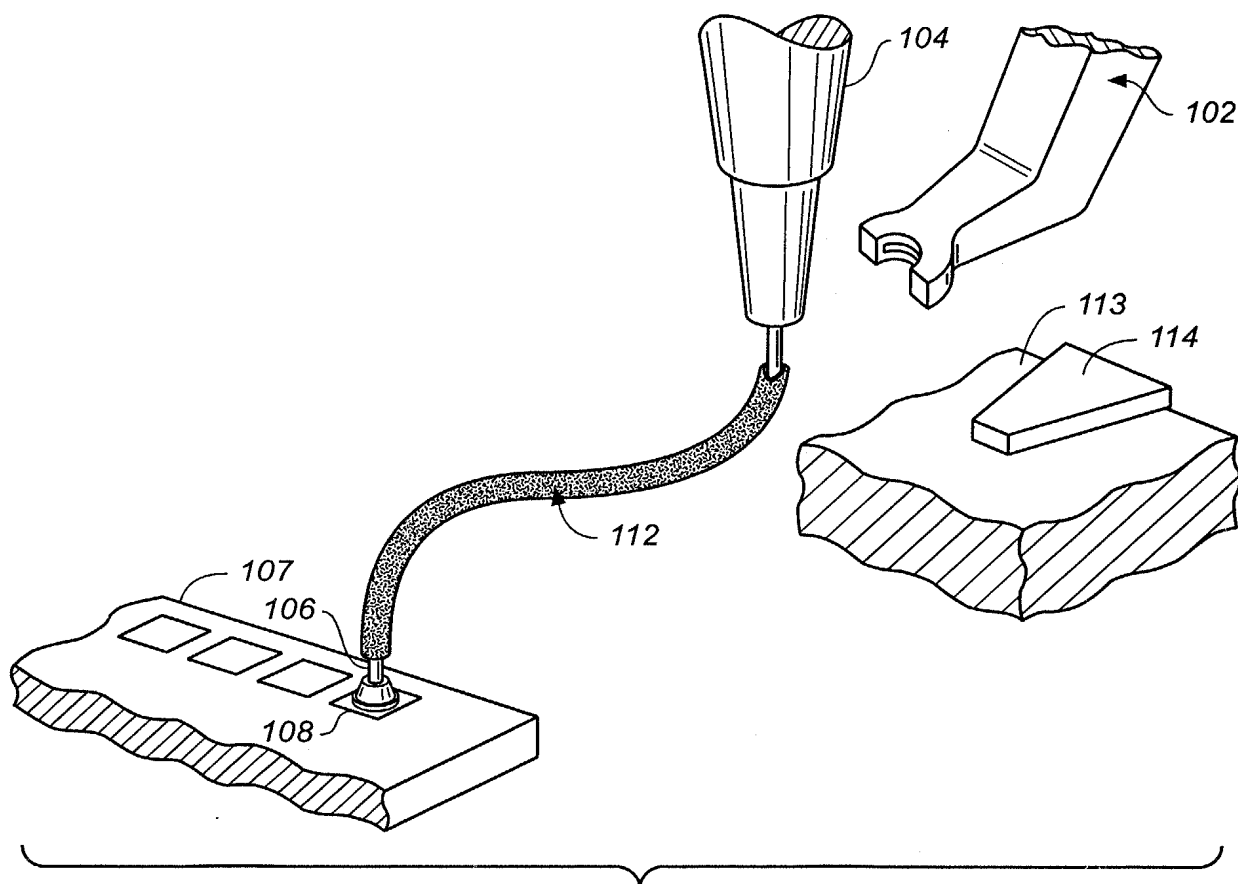


FIG._4



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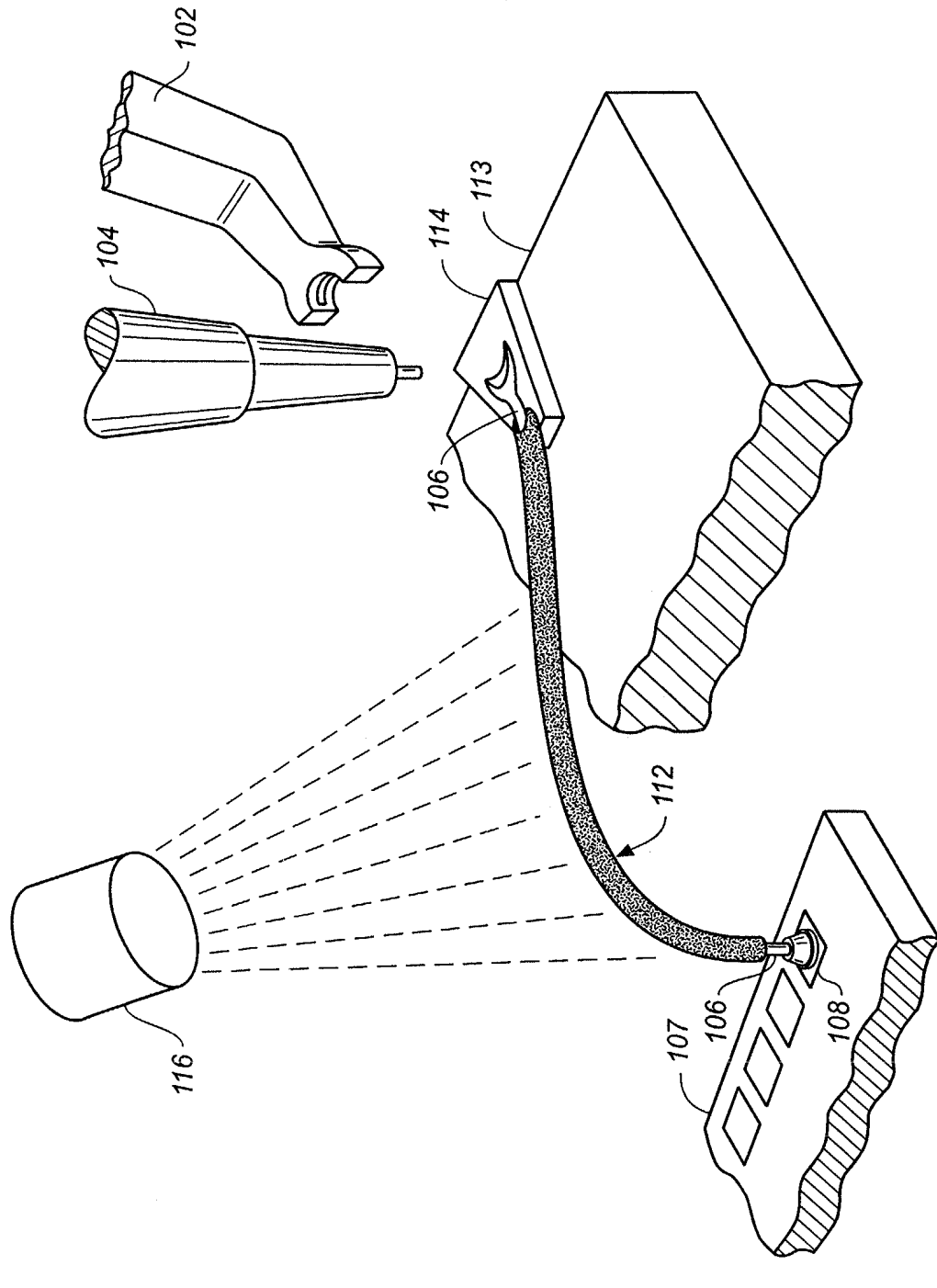


FIG. 5